

2PA1576

PNP general-purpose transistor

Rev. 06 — 17 November 2009

Product data sheet

1. Product profile

1.1 General description

PNP transistor in a SOT323 (SC-70) plastic package. The NPN complement is 2PC4081.

1.2 Features

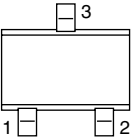
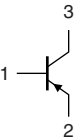
- Low current (max. 150 mA)
- Low voltage (max. 50 V)
- Low collector capacitance (typ. 2.5 pF)

1.3 Applications

- General-purpose switching and amplification

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	base		 <i>sym013</i>
2	emitter		
3	collector		

3. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
2PA1576Q	SC-70	plastic surface mounted package; 3 leads	SOT323
2PA1576R			
2PA1576S			

4. Marking

Table 3. Marking codes

Type number	Marking code ^[1]
2PA1576Q	F*Q
2PA1576R	F*R
2PA1576S	F*S

[1] * = -: made in Hong Kong
* = t: made in Malaysia

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-60	V
V_{CEO}	collector-emitter voltage	open base	-	-50	V
V_{EBO}	emitter-base voltage	open collector	-	-6	V
I_C	collector current (DC)		-	-150	mA
I_{CM}	peak collector current		-	-200	mA
I_{BM}	peak base current		-	-200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	^[1] -	200	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		^[1] -	-	625	K/W

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 6. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit				
I_{CBO}	collector-base cut-off current	$I_E = 0\text{ A}; V_{CB} = -30\text{ V}$	-	-	-100	nA				
		$I_E = 0\text{ A}; V_{CB} = -30\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	-5	μA				
I_{EBO}	emitter-base cut-off current	$I_C = 0\text{ A}; V_{EB} = -4\text{ V}$	-	-	-100	nA				
h_{FE}	DC current gain	$I_C = -1\text{ mA}; V_{CE} = -6\text{ V}$								
							2PA1576Q	120	-	270
							2PA1576R	180	-	390
							2PA1576S	270	-	560
V_{CEsat}	collector-emitter saturation voltage	$I_C = -50\text{ mA}; I_B = -5\text{ mA}$	[1]	-	-500	mV				
C_c	collector capacitance	$I_E = i_e = 0\text{ A}; V_{CB} = -12\text{ V}; f = 1\text{ MHz}$	-	2.5	3.5	pF				
f_T	transition frequency	$I_C = -2\text{ mA}; V_{CE} = -12\text{ V}; f = 100\text{ MHz}$	100	-	-	MHz				

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

8. Package outline

Plastic surface-mounted package; 3 leads

SOT323

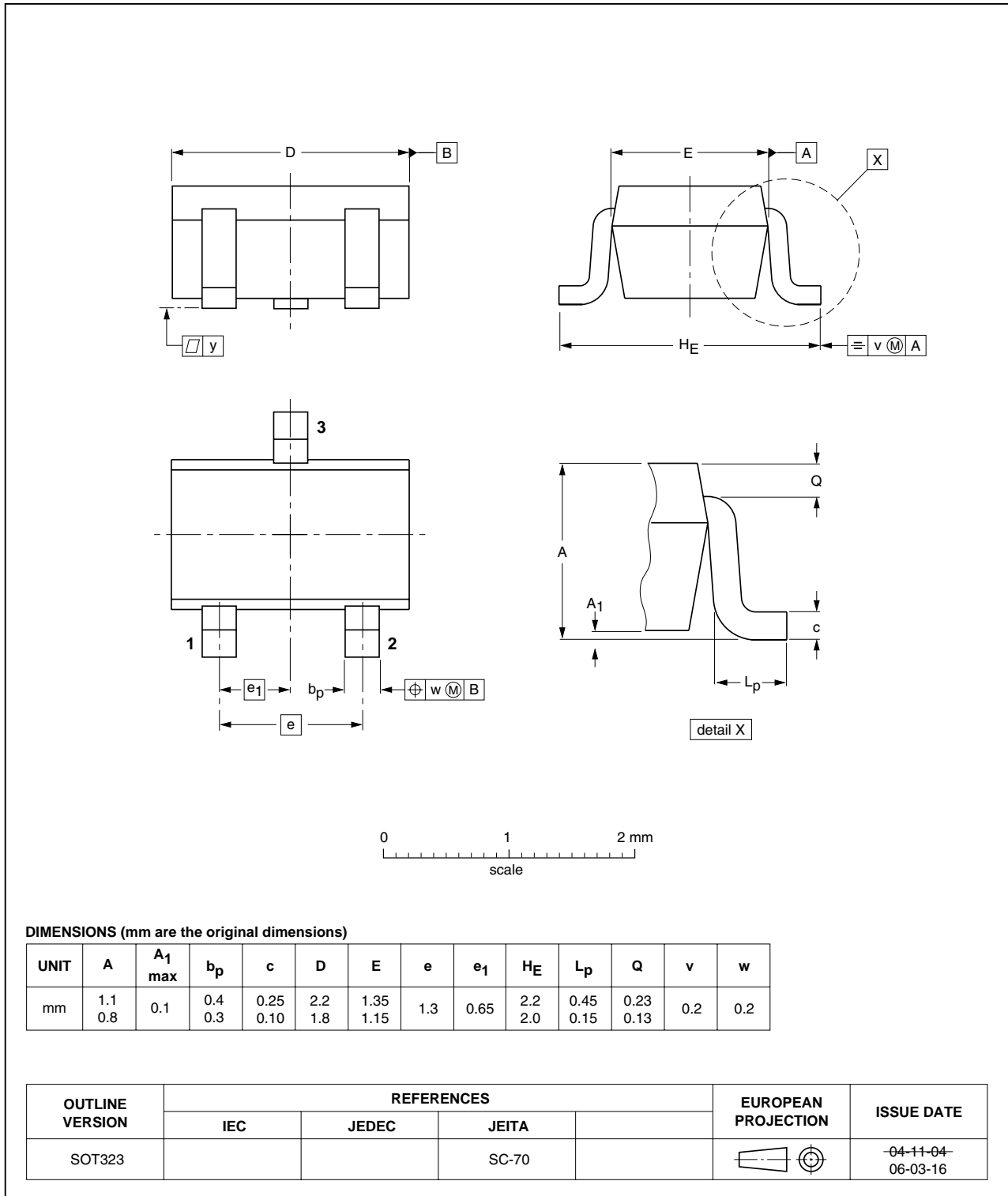


Fig 1. Package outline SOT323 (SC-70)

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PA1576_6	20091117	Product data sheet	-	2PA1576_5
Modifications:		<ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.Figure 1 "Package outline SOT323 (SC-70)": updated		
2PA1576_5	20041124	Product data sheet	-	2PA1576_4
2PA1576_4	19990531	Product specification	-	2PA1576_3
2PA1576_3	19970328	Objective specification	-	2PA1576_2
2PA1576_2	19931213	n.a.	-	n.a.

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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12. Contents

1	Product profile	1
1.1	General description	1
1.2	Features	1
1.3	Applications	1
2	Pinning information	1
3	Ordering information	1
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	2
7	Characteristics	3
8	Package outline	4
9	Revision history	5
10	Legal information	6
10.1	Data sheet status	6
10.2	Definitions	6
10.3	Disclaimers	6
10.4	Trademarks	6
11	Contact information	6
12	Contents	7

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